THERMINIC 2025

CALL FOR PAPERS

NAPLES | SEPTEMBER 24–26, 2025

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The 31st THERMINIC Workshop will be held in Naples, Italy. THERMINIC is the major European Workshop related to thermal and reliability issues in electronic components and systems. For academics and industrialists involved in micro and power electronics this annual event promises to be a very special occasion with a high quality technical programme and exciting social events. We invite delegates to consider submitting abstracts that are related, but not limited to, the following topics:

Thermal Phenomena in Simulation & Experiment:

- Thermal management of electronic components and systems
- Classical and modern thermometry and thermography
- Thermal interface materials and their characterisation
- Thermal modelling and investigation of packages
- Nano-scale heat transfer
- Multi-physics simulation and field coupling
- Electro-thermal modelling and simulation
- CFD modelling and benchmarking
- Advanced thermal materials and technologies
- Numerical methods for multi-scale heat transfer
- Use of novel, advanced mathematics and statistics concepts / AI methods for complex digital twins of components and systems

Electronics Cooling Concepts & Applications:

- Cooling concepts: air, liquid, 2-phase, etc.
- Power electronics
- High temperature electronics
- Solid state lighting LED packages and LED based lighting solutions
- Thermo-electric and sub-ambient cooling
- Novel and advanced cooling technologies
- Heat pipe and vapor chambers
- 3D heterogenous integration and cooling, ultra low form factor air cooling
- Novel manufacturing methods
- Cooling for IoT, CPS, mobile, edge computing
- Thermal buffering for computational sprinting
- Battery thermal management

Thermo-Mechanical Reliability

- Thermo-mechanical reliability
- Prognostics and health monitoring
- Lifetime modelling and prediction
- Damage and fracture mechanics
- Failure analysis and inline inspection

Please upload your paper at:
www.conftool.pro/therminic2025

The technical programme will include oral talks, poster presentations, special sessions and invited keynote talks given by renowned speakers. We will again offer a professional development course (PDC) on the day before the workshop.

Authors are invited to submit an abstract describing recent work. Abstracts must detail the objectives of the work presented and demonstrate new results. All abstracts will be double-blind reviewed. There will be best paper and best poster awards.

Please, refer to the **www.therminic2025.eu** web page for information on past THERMINIC workshops. Accepted papers will be submitted for inclusion into IEEE Xplore subject to meeting IEEE Xplore's scope and quality requirements. THERMINIC papers can be searched through IEEE, Google scholar and other search engines. Vendors and Book Exhibitors are invited to offer products in the scope of the Workshop. Exhibitor space is available – please contact local committee for further details. Editors are invited to exhibit books.

Deadline abstract submission: 04th April 2025
Notification of acceptance: 13h June 2025
Submission of paper for workshop proceedings: 8th August 2025

Venue

Centro Congressi (Conference Center)
of University of Naples Federico II
Via Partenope, 36, 80121 Naples
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Contact

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